

## **Varistor**

# **Material Data Sheet**

Product Class:	Disk Varistor S* B722xxS/P*V87 B723xxS/P*V87
oto.	B723xxS/P*V87 10.12.2020
Date IMDS ID	10.12.2020
if available	
Version:	5.10

Product Part (IMDS: semi component)	Material Class (IMDS: Material)	Material (Classification) VDA 231	Substance	TMPS**) [wt%]	CAS if applicable	typical mass of material [wt-%]	Traces see 1)
Active Part	Ceramic	3B	ZnO Bi2O3 Sb2O3 Co3O4 NiO others*)	91 4,0 2,5 1 0,5	1314-13-2 1304-76-3 1309-64-4 1308-06-1 1313-99-1	45	
Termination	Composite	4D	Cu or Ag	95	7440-50-8 7440-22-4	0,5	
			Glass frit (boro-silicate)	5			
Solder	Heavy Metal	1C8	Sn Ag Cu	96,5 3 0,5	7440-31-5 7440-22-4 7440-50-8	4,5	
Leads	Heavy Metal	1A	Fe	100	7439-89-6	27,5	
	Heavy Metal	1C12	Cu	100	7440-50-8	4,9	
	Heavy Metal	1C8	Sn	100	7440-31-5	1,6	
Encapsulation	Duromer	2D Halogen-free coating	SiO2 Epoxy Pyromellitic dianhydride Phosphated epoxy others*)	46 40 6,5 5 2,5	60676-86-0 25036-25-3 89-32-7	16	
	ı		ı		Sum in total:	100	

sizes [mm]	weight range [g]	material numbers	sizes [ mm]	weight range [g]	material numbers	sizes [ mm]	weigl	ht range [ g ]	material numbers
7	0.3 - 0.7	B72205S*V87	13.0	1.0 - 3.0	B722/B72310S/P	23.0	2.7 –	15.7	B722/B72320S/P*V87
9	0.4 - 1.1	B722/B72307S*V8			*V87	27.5	5.2 –	22.2	B72225S*V87
		7	17.0	1.4 - 7.6	B72214S/P*V87				

#### Not part of a Product Class

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<sup>\*)</sup> others: .(not declarable or prohibited substances acc. GADSL)

### Important remarks:

The declaration limit is 0.1% as defined by IEC 62474 (IEC PAS 61906). Traces are product parts, substances etc. that are below a percentage of 0.1 % by weight, if not otherwise

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The products set forth herein are "RoHS-compatible". RoHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

#### RoHS - Exemptions for the Product Class / Product according to Annex III: ( ☑ valid ☐ not valid )

#### ☑ no exemptions;

☐ Exemption 6 (a):  $Lead \ as \ an \ alloying \ element \ in \ steel \ for \ machining \ purposes \ and \ in \ galvanized \ steel \ containing \ up \ to \ 0,35 \ \% \ lead \ by \ weight;$ 

☐ Exemption 6 (b): Lead as an alloying element in aluminium containing up to 0,4 % lead by weight;

☐ Exemption 6 (c): Copper alloy containing up to 4 % lead by weight;

□ Exemption 7 (a): Lead in high melting temperature type solder (i.e. lead-based alloys containing 85 % by weight or more lead);

🗆 Exemption 7 (c)-1: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound;

☐ Exemption 7 (c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher;

☐ Exemption 7 (c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC;

Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages;

 $\hfill\square$  Other Exemption than above .

<sup>\*\*)</sup> typical mass percentage of substance